

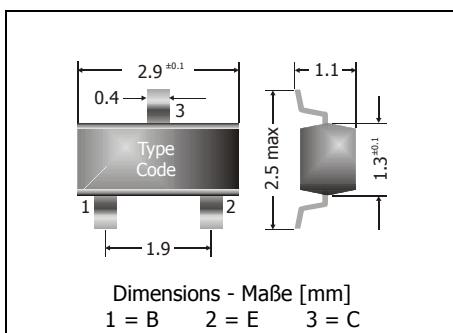
## BC856 ... BC860

**PNP**

**Surface Mount General Purpose Si-Epi-Planar Transistors**  
**Si-Epi-Planar Universaltransistoren für die Oberflächenmontage**

**PNP**

Version 2011-11-07



Power dissipation – Verlustleistung

250 mW

Plastic case

SOT-23

Kunststoffgehäuse

(TO-236)

Weight approx. – Gewicht ca.

0.01 g

Plastic material has UL classification 94V-0  
Gehäusematerial UL94V-0 klassifiziertStandard packaging taped and reeled  
Standard Lieferform gegurtet auf Rolle

### Maximum ratings ( $T_A = 25^\circ\text{C}$ )

			<b>BC856</b>	<b>BC857 BC860</b>	<b>BC858 BC859</b>
Collector-Emitter-volt. – Kollektor-Emitter-Spannung	B open	- $V_{CEO}$	65 V	45 V	30 V
Collector-Base-voltage – Kollektor-Basis-Spannung	E open	- $V_{CBO}$	80 V	50 V	30 V
Emitter-Base-voltage – Emitter-Basis-Spannung	C open	- $V_{EBO}$		5 V	
Power dissipation – Verlustleistung		$P_{tot}$		250 mW <sup>1)</sup>	
Collector current – Kollektorstrom (dc)		- $I_C$		100 mA	
Peak Collector current – Kollektor-Spitzenstrom		- $I_{CM}$		200 mA	
Junction temperature – Sperrsichttemperatur		$T_j$		-55...+150°C	
Storage temperature – Lagerungstemperatur		$T_s$		-55...+150°C	

### Characteristics ( $T_j = 25^\circ\text{C}$ )

			<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>
DC current gain – Kollektor-Basis-Stromverhältnis					
- $V_{CE} = 5 \text{ V}$ , - $I_C = 10 \mu\text{A}$	Group A	$H_{FE}$	–	90	–
	Group B	$h_{FE}$	–	150	–
	Group C	$h_{FE}$	–	270	–
- $V_{CE} = 5 \text{ V}$ , - $I_C = 2 \text{ mA}$	Group A	$H_{FE}$	125	180	250
	Group B	$h_{FE}$	220	290	475
	Group C	$h_{FE}$	420	520	800
Collector-Emitter saturation voltage – Kollektor-Sättigungsspannung <sup>2)</sup>					
$I_C = 10 \text{ mA}$ , $I_B = 0.5 \text{ mA}$	- $V_{CEsat}$	–	–	300 mV	
$I_C = 100 \text{ mA}$ , $I_B = 5 \text{ mA}$	- $V_{CEsat}$	–	–	650 mV	
Base-Emitter saturation voltage – Basis-Sättigungsspannung <sup>2)</sup>					
$I_C = 10 \text{ mA}$ , $I_B = 0.5 \text{ mA}$	- $V_{BEsat}$	–	700 mV	–	
$I_C = 100 \text{ mA}$ , $I_B = 5 \text{ mA}$	- $V_{BEsat}$	–	900 mV	–	

1) Mounted on P.C. board with 3 mm<sup>2</sup> copper pad at each terminal  
 Montage auf Leiterplatte mit 3 mm<sup>2</sup> Kupferbelag (Löt pad) an jedem Anschluss

2) Tested with pulses  $t_p = 300 \mu\text{s}$ , duty cycle  $\leq 2\%$  – Gemessen mit Impulsen  $t_p = 300 \mu\text{s}$ , Schaltverhältnis  $\leq 2\%$

**Characteristics ( $T_j = 25^\circ\text{C}$ )****Kennwerte ( $T_j = 25^\circ\text{C}$ )**

		<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>
Base-Emitter-voltage – Basis-Emitter-Spannung <sup>2)</sup>				
- $V_{CE} = 5 \text{ V}, I_C = - 2 \text{ mA}$ - $V_{CE} = 5 \text{ V}, I_C = - 10 \text{ mA}$	- $V_{BE}$ - $V_{BE}$	600 mV –	– –	750 mV 720 mV
Collector-Base cutoff current – Kollektor-Basis-Reststrom				
- $V_{CB} = 30 \text{ V}, (\text{E open})$ - $V_{CE} = 30 \text{ V}, T_j = 125^\circ\text{C}, (\text{E open})$	- $I_{CBO}$ - $I_{CBO}$	– –	– –	15 nA 4 $\mu\text{A}$
Emitter-Base cutoff current				
- $V_{EB} = 5 \text{ V}, (\text{C open})$	- $I_{EBO}$	–	–	100 nA
Gain-Bandwidth Product – Transitfrequenz				
- $V_{CE} = 5 \text{ V}, - I_C = 10 \text{ mA}, f = 100 \text{ MHz}$	$f_T$	100 MHz	–	–
Collector-Base Capacitance – Kollektor-Basis-Kapazität				
- $V_{CB} = 10 \text{ V}, I_E = i_e = 0, f = 1 \text{ MHz}$	$C_{CBO}$	–	–	4.5 pF
Emitter-Base Capacitance – Emitter-Basis-Kapazität				
- $V_{EB} = 0.5 \text{ V}, I_C = i_c = 0, f = 1 \text{ MHz}$	$C_{EBO}$	–	9 pF	–
Noise figure – Rauschzahl				
- $V_{CE} = 5 \text{ V}, - I_C = 200 \mu\text{A}$ $R_G = 2 \text{ k}\Omega, f = 1 \text{ kHz}, \Delta f = 200 \text{ Hz}$	BC856 ... BC858 BC859 ... BC860	F F	– –	2 dB 1.2 dB 10 dB 4 dB
Thermal resistance junction to ambient air Wärmewiderstand Sperrsicht – umgebende Luft	$R_{thA}$	< 420 K/W <sup>1)</sup>		
Recommended complementary NPN transistors Empfohlene komplementäre NPN-Transistoren	BC846 ... BC850			
Marking of available current gain groups Stempelung der lieferbaren Stromverstärkungsgruppen	BC856A = 3A BC856B = 3B BC856C = 3C	BC857A = 3E BC857B = 3F BC857C = 3G	BC858A = 3E BC858B = 3F BC858C = 3G	BC859B = 3F BC859C = 3G or 4C
		BC860B = 3F BC860C = 3G or 4G		

2 Tested with pulses  $t_p = 300 \mu\text{s}$ , duty cycle  $\leq 2\%$  – Gemessen mit Impulsen  $t_p = 300 \mu\text{s}$ , Schaltverhältnis  $\leq 2\%$

1 Mounted on P.C. board with  $3 \text{ mm}^2$  copper pad at each terminal  
Montage auf Leiterplatte mit  $3 \text{ mm}^2$  Kupferbelag (Lötpad) an jedem Anschluss